

Physik Instrumente

As Photonics Applications Multiply, New Ways to Subtract Costs

Scott Jordan
Head of Photonics
PI

- ~1700 Employees
- 15 Subsidiaries
- Design & Service Centers in USA, Asia, Europe
- >100 man Years of Alignment Expertise
- Privately Owned – Not Driven by Quarterly Results
- Focused on Long Term Relationships w/Customers & Suppliers



The PI Group

Precision Automation, Nanopositioning, Piezo Technology

Americas

North America
Central America
South America

Europe

PI UK
PI France
PI Italy
miCos Iberia
PI Benelux

Germany

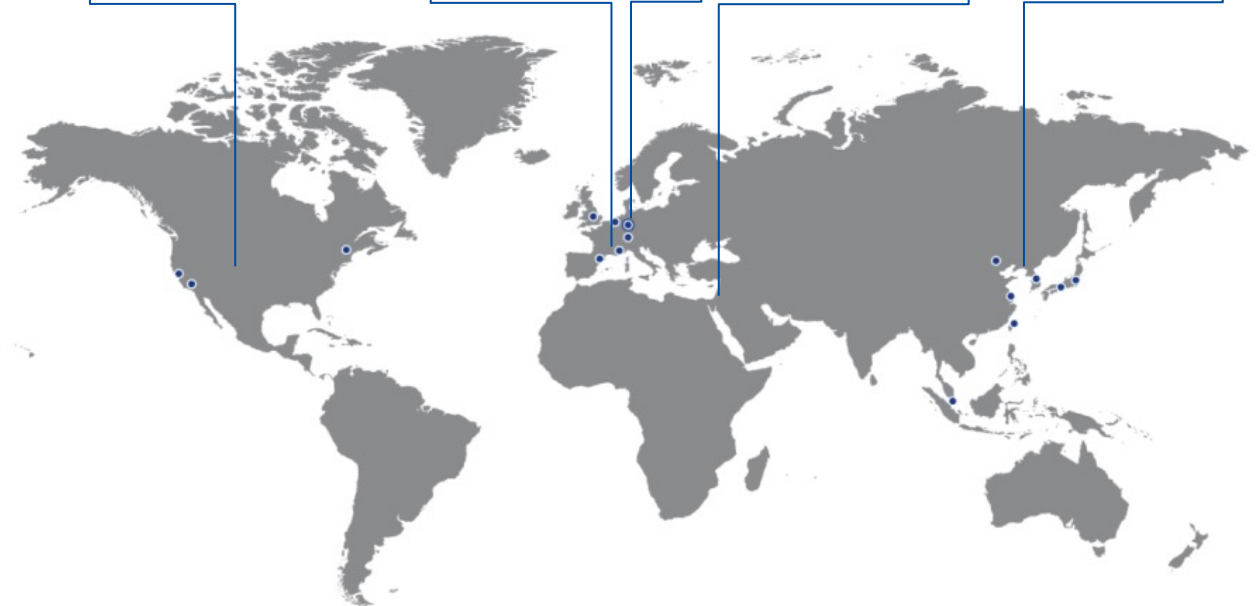
PI Karlsruhe
PI Ceramic
PI miCos

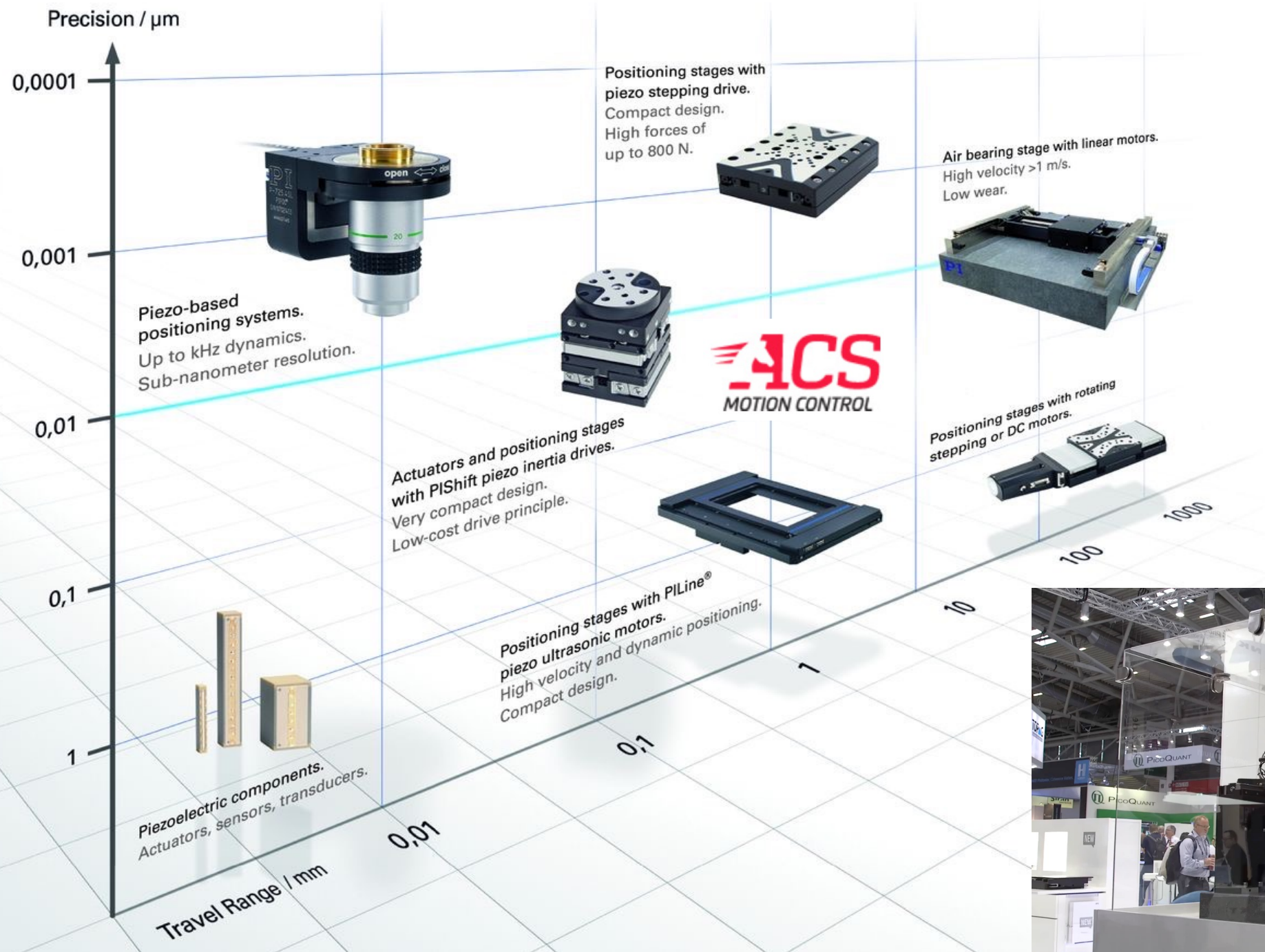
Israel



Asia

PI Japan
PI Shanghai
PI Singapore
PI Taiwan
PI Korea



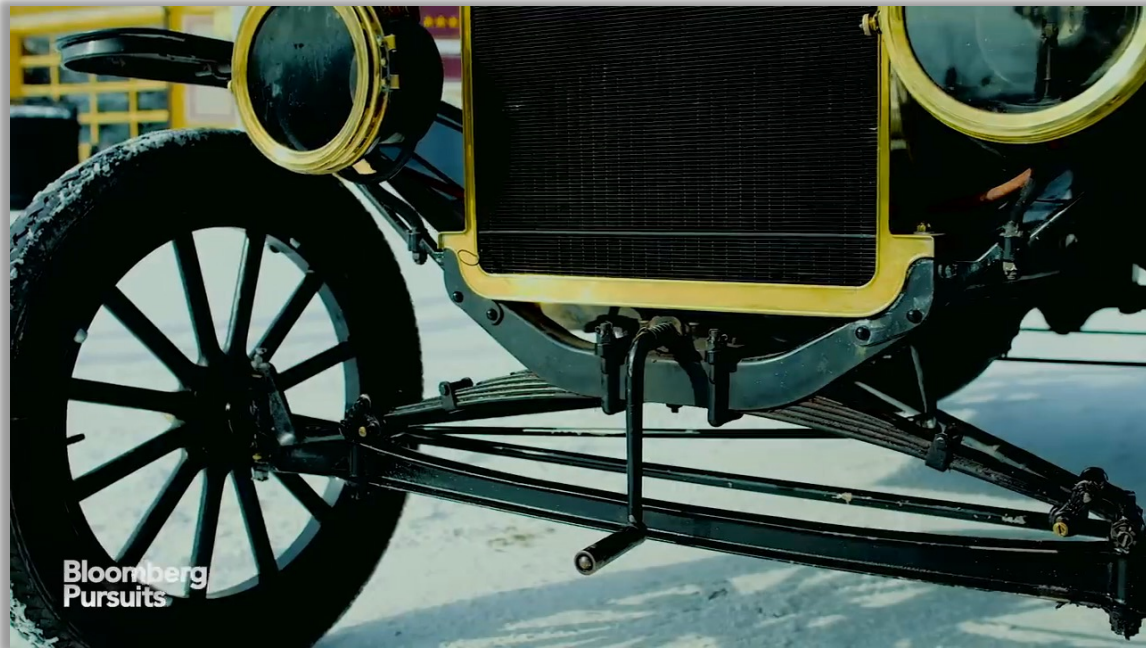


PI's Engineered Systems Group Builds World-Class Automation Platforms



After Motion Control: *Micro-Robotics*

Built-in functionality *and intelligence* mark the future (and not just for motion control)



Courtesy Bloomberg
"Driving a Ford Model T Is a Lot Harder Than You'd Think!"



"Do what I tell you to do"

- Accelerate
- Brake
- Turn...



Courtesy Tesla
"Full Self-Driving"



"Do what I want you to do"

- Go to Aldi

"10 exabytes per month"
--VisualCapitalist.com



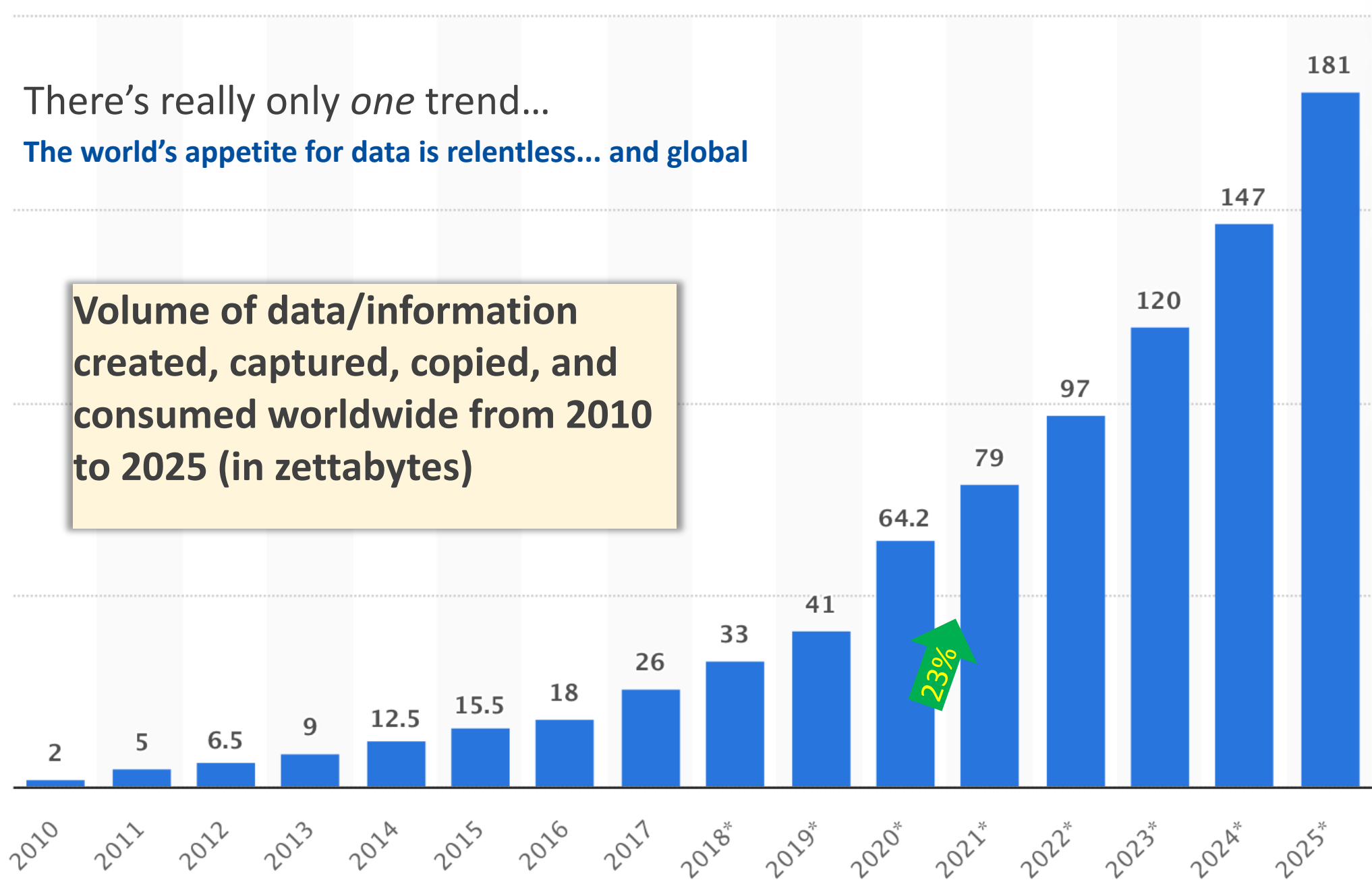
Throughout:
Latest available
data from credible
sources

<https://www.statista.com/statistics/871513/worldwide-data-created/>

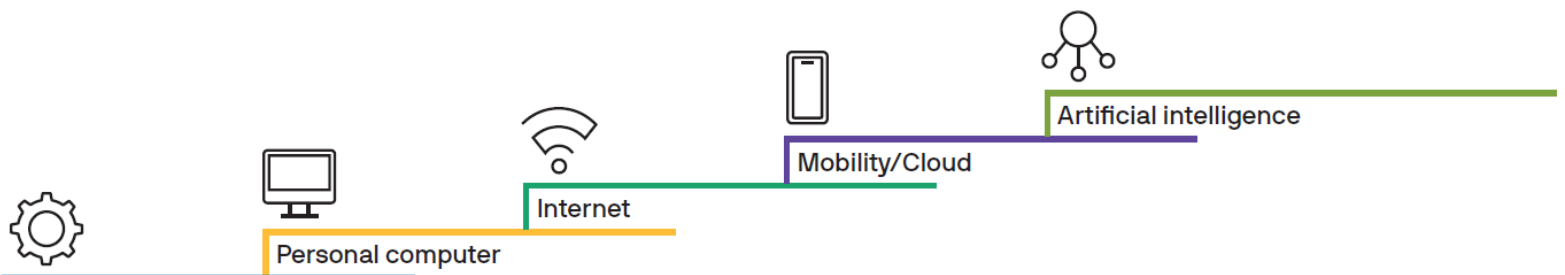


There's really only *one* trend...
The world's appetite for data is relentless... and global

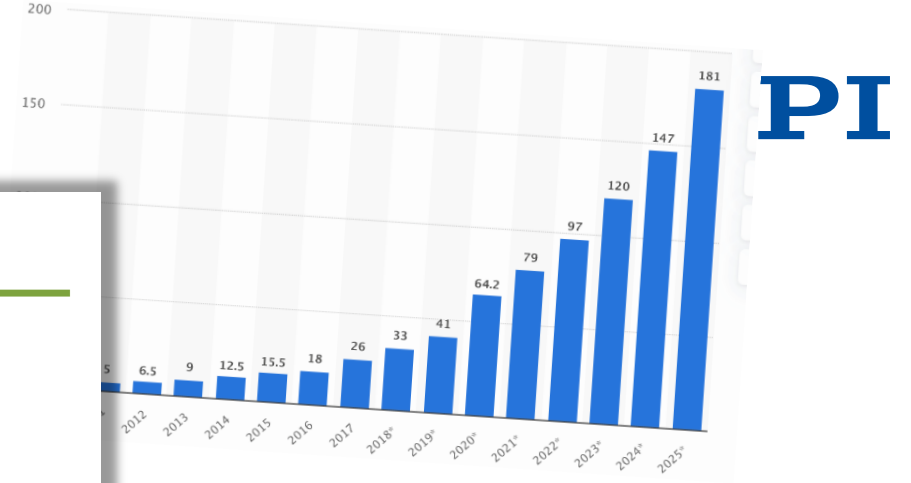
**Volume of data/information
created, captured, copied, and
consumed worldwide from 2010
to 2025 (in zettabytes)**



AI: The new accelerant



Mainframe		Personal computer		Internet		Mobility/Cloud		Artificial intelligence	
1980		1990		2000		2010		2020	
Company	Mkt cap (USD bn)	Company	Mkt cap (USD bn)	Company	Mkt cap (USD bn)	Company	Mkt cap (USD bn)	Company	Mkt cap (USD bn)
IBM	38	IBM	54	Microsoft	604	Microsoft	269	Apple	2,232
Eastman Kodak	8	Panasonic	33	Cisco Systems	355	Google	197	Microsoft	1,682
Xerox	5	Toshiba	27	Intel	274	Apple	191	Amazon	1,634
Hewlett-Packard	4	NEC	19	Lucent Technologies	238	IBM	171	Alphabet	1,185
Emerson Electric	2	Fujitsu	19	Nokia	210	Cisco Systems	138	Facebook	778
Texas Instruments	2	Mitsubishi Electric	16	IBM	193	Oracle	123	Tencent	698
Motorola Solutions	2	Eastman Kodak	13	Oracle	158	Hewlett-Packard	122	Tesla	669
Nortel Networks	2	Sanyo Electric	13	Nortel Networks	139	Intel	113	Alibaba	649
Intel	1	FUJIFILM Holdings	12	Sun Microsystems	135	Samsung	88	Samsung	501
Harris	1	Hewlett-Packard	11	Dell	130	QUALCOMM	77	TSMC	489

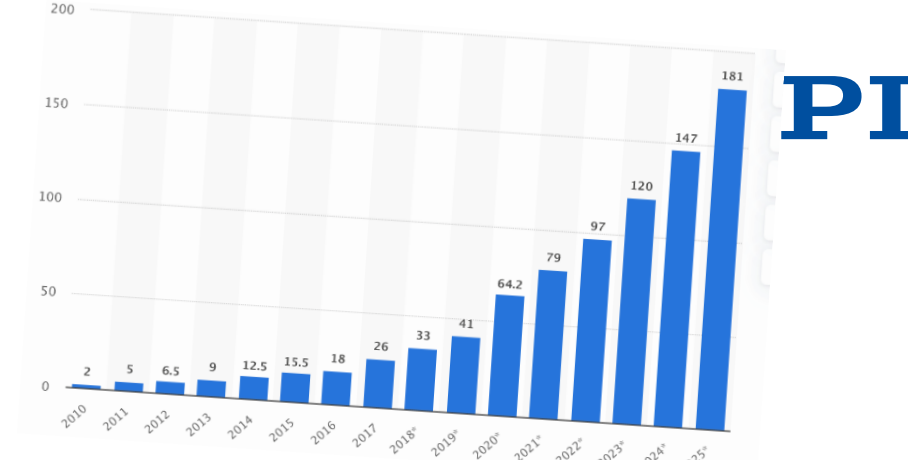


“Often, when a major platform shift occurs – think mainframes to minicomputers, PCs to mobile devices, CPUs to GPUs (central processing units to graphics processing units) – it creates entirely new pools of demand. In the next few years, we expect a record pace of new, densely packed, high powered data center builds. These will be filled with GPUs, custom silicon, advanced memory packages and photonics to support network bandwidth.”

--[J.P. Morgan Asset Management](#), 10/2023



mm-scale to planetary scale,
humanity's appetite for data drives Photonics



"...a chip maker could build a co-packaged optical transceiver on to the edge of a package, and then use UCle to connect it to another chiplet..." --Anandtech

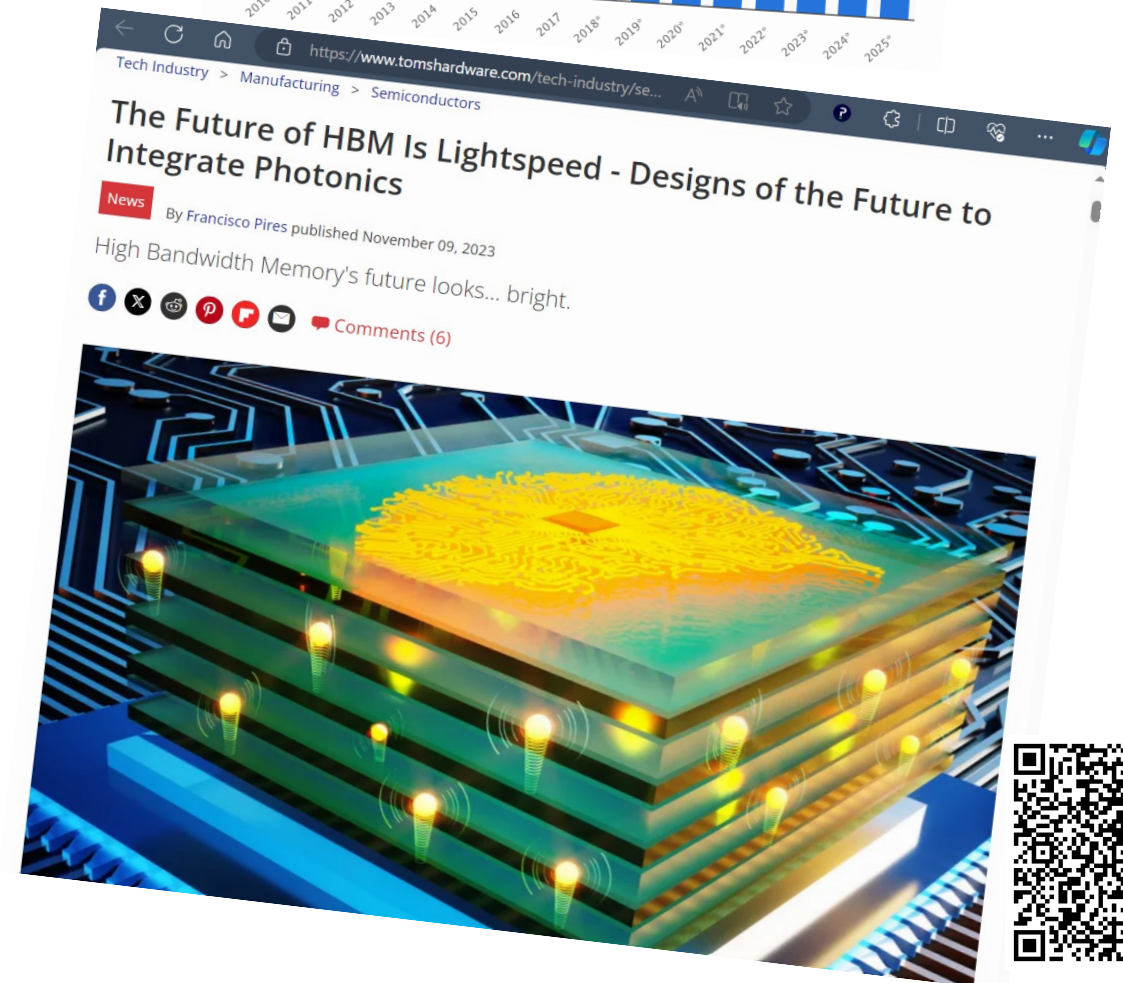
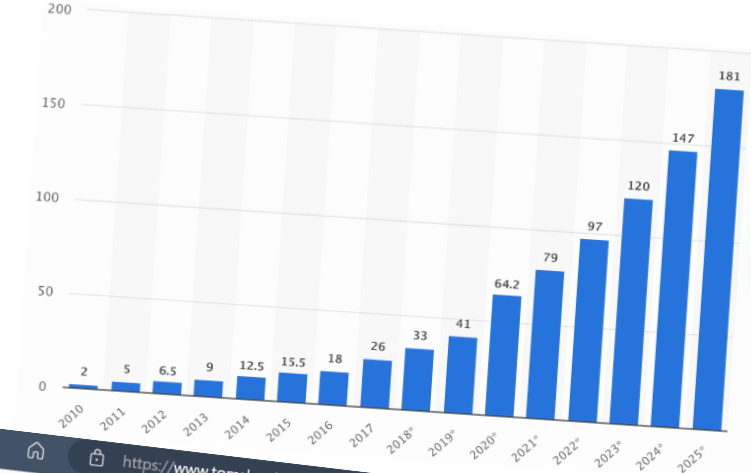


"Good ideas are always crazy until they're not."
--Elon Musk

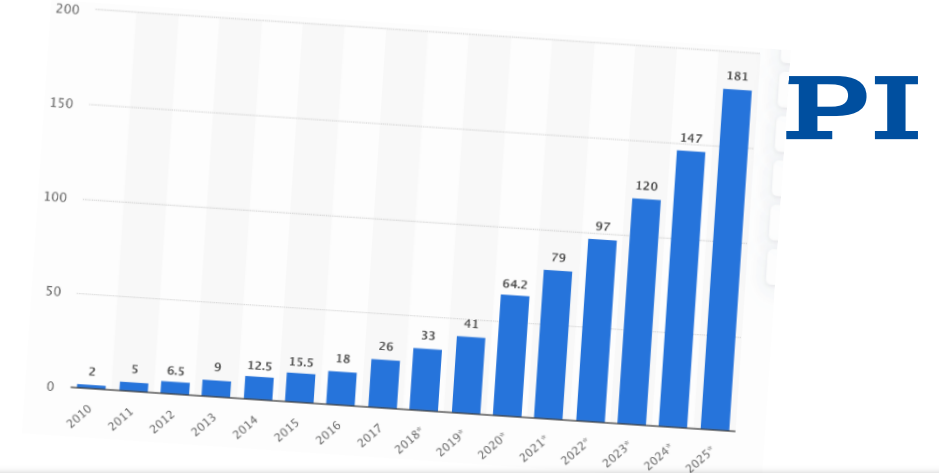
mm-scale to planetary scale,
humanity's appetite for data drives Photonics



"...a chip maker could build a co-packaged optical transceiver on to the edge of a package, and then use UCle to connect it to another chiplet..." --Anandtech



mm-scale to planetary scale,
humanity's appetite for data drives Photonics



“Introducing inter-chip optical interconnects could obliterate bandwidth and capacity limitations coming from today’s copper interconnects, which are hampered by impedance mismatches between the CPU and the dual-inline memory modules.”

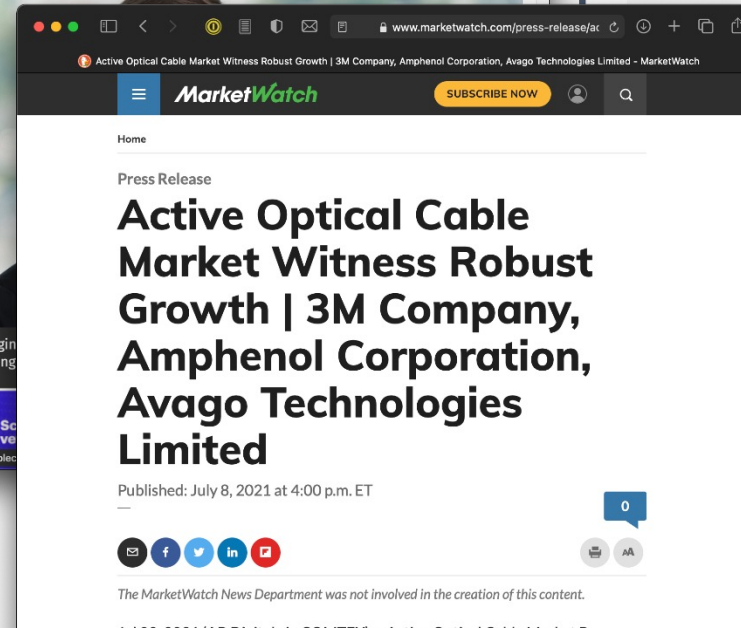
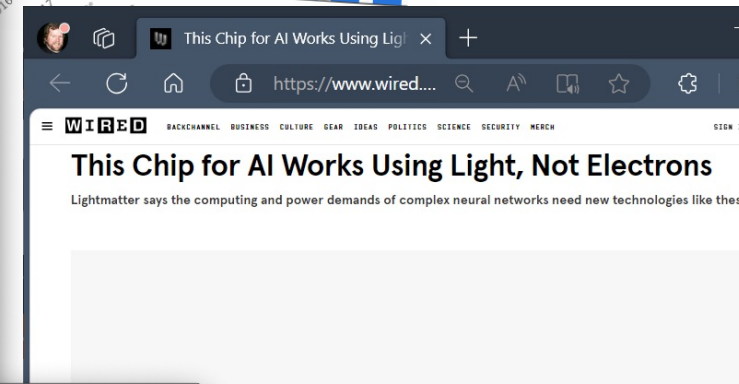
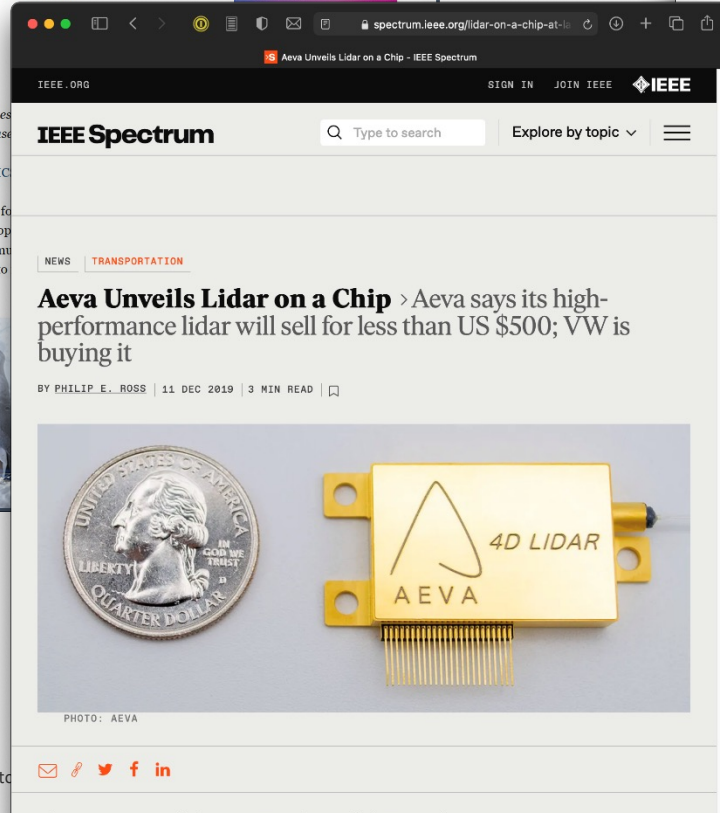
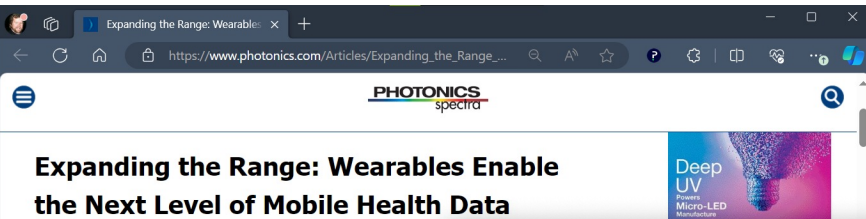
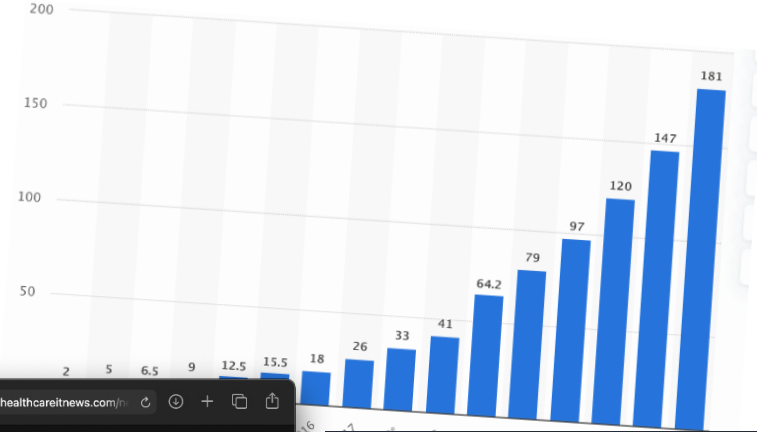
--Dongjae Shin, Samsung, at PIC 2019



Observation:

Silicon Photonics is *not just about the data center anymore*

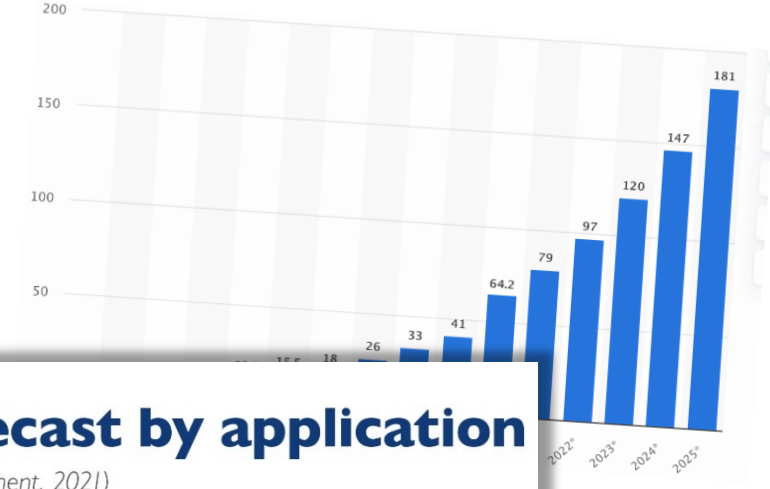
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Driving Photonics: New applications

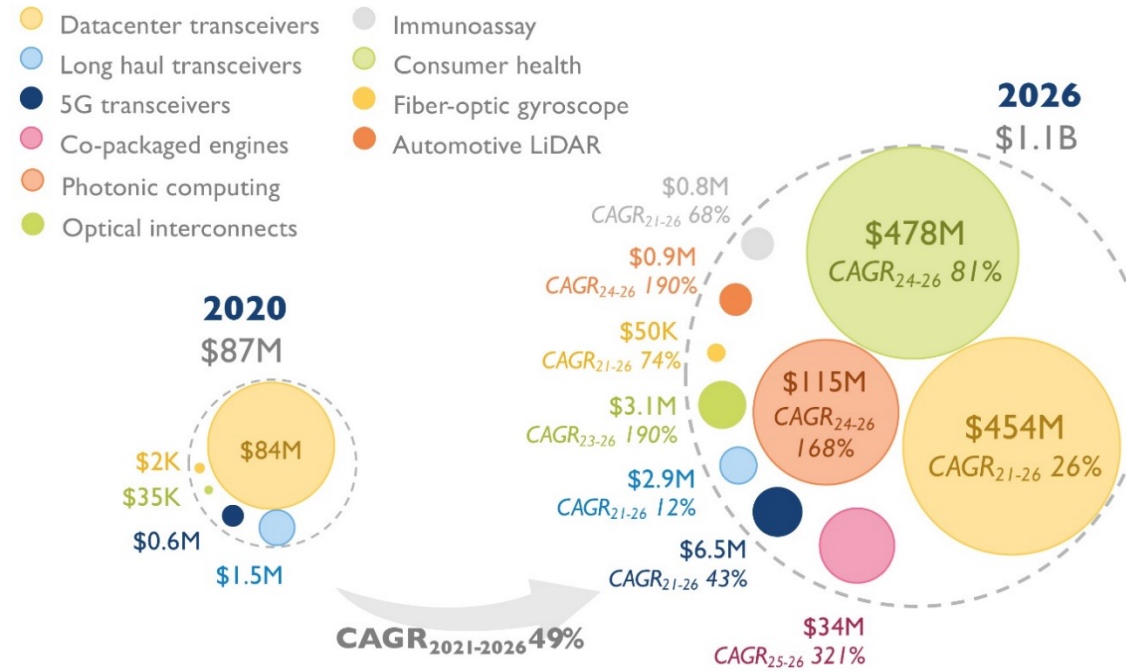
→ *no single point of market failure*

PI



2020-2026 silicon photonics die forecast by application

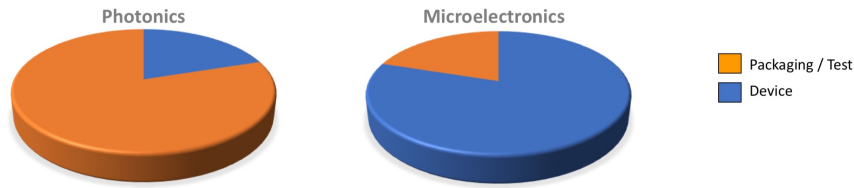
(Source: Silicon Photonics 2021 report, Yole Développement, 2021)



Alignment: The Repetitive Cost

Cost breakdown

Packaging cost is a big piece of the pie for Photonics
Microelectronic packaging is geared towards low cost



Packaging is key to lower cost of photonics

Leverage the microelectronic industry



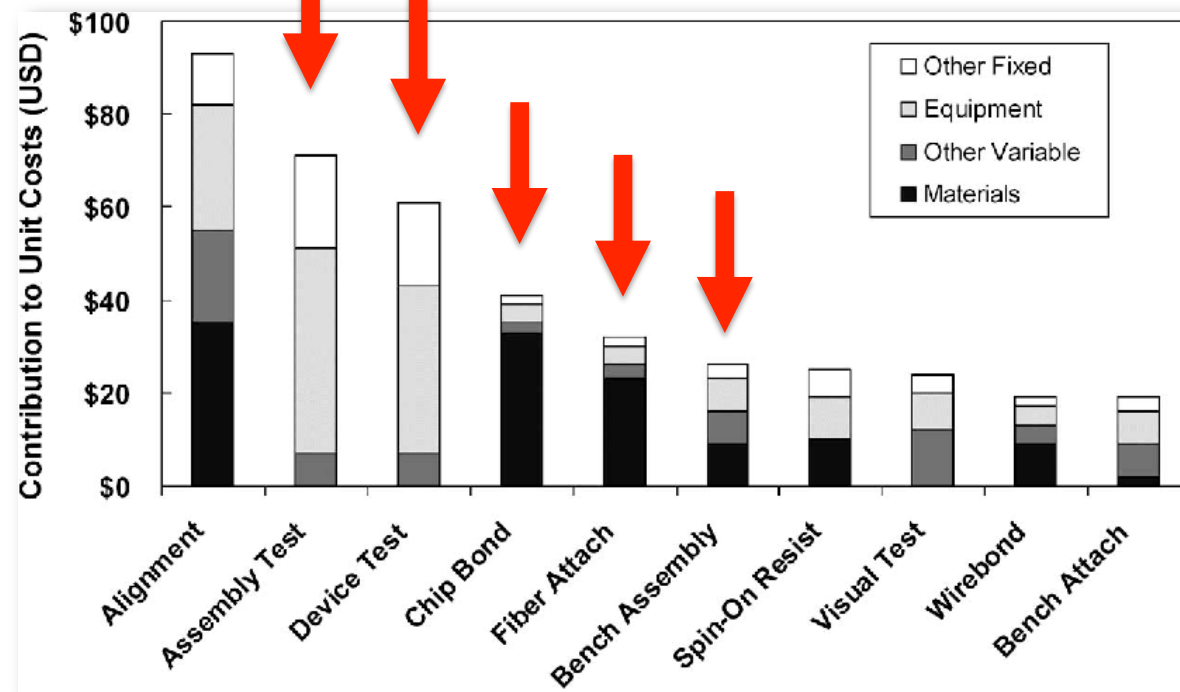
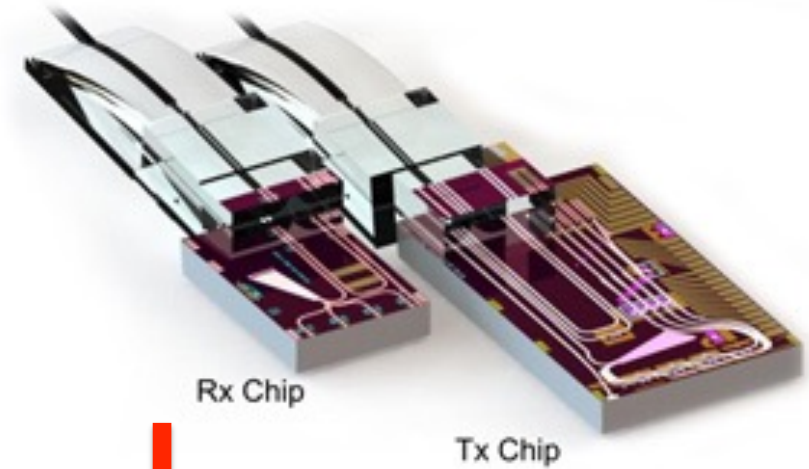
Photonics Summit, Cadence, 6th September 2017, San Jose CA



“Automated High-Throughput Assembly for Photonic Packaging”, Barwicz et al, *Photonics Summit*, Cadence, 2017, https://www.cadence.com/content/dam/cadence-www/global/en_US/documents/company/Events/summits/photonics/fortier-2017.pdf



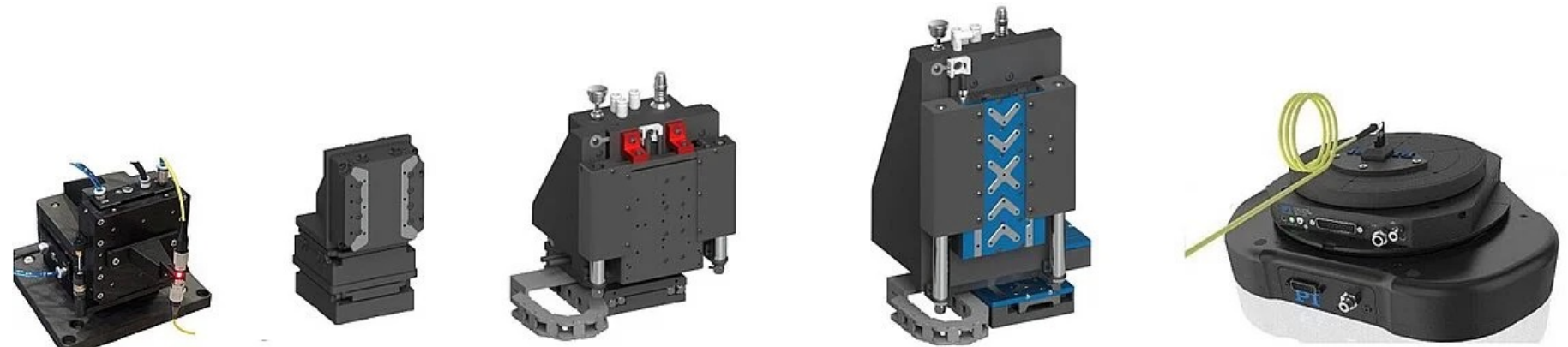
“Process-based cost modeling of photonics manufacture...”, E. Fuchs et al, *J. Lightwave Tech.*, 2006, <https://www.semanticscholar.org/paper/Process-based-cost-modeling-of-photonics-the-cost-a-Fuchs-Bruce/125e24b2e2e71860f088526441ee5ce16e6ce42c>

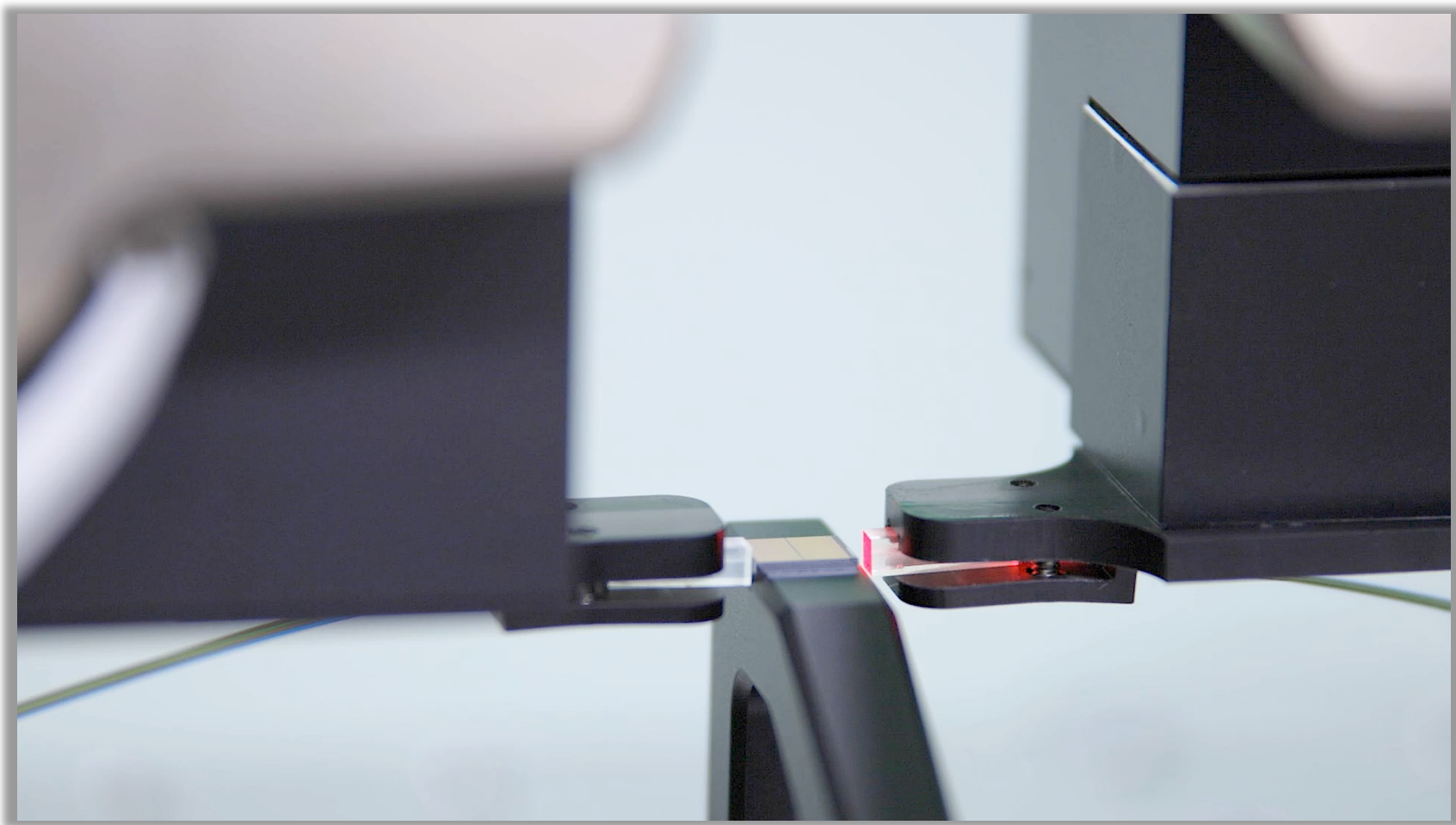


A Modular Approach to Meet all Needs

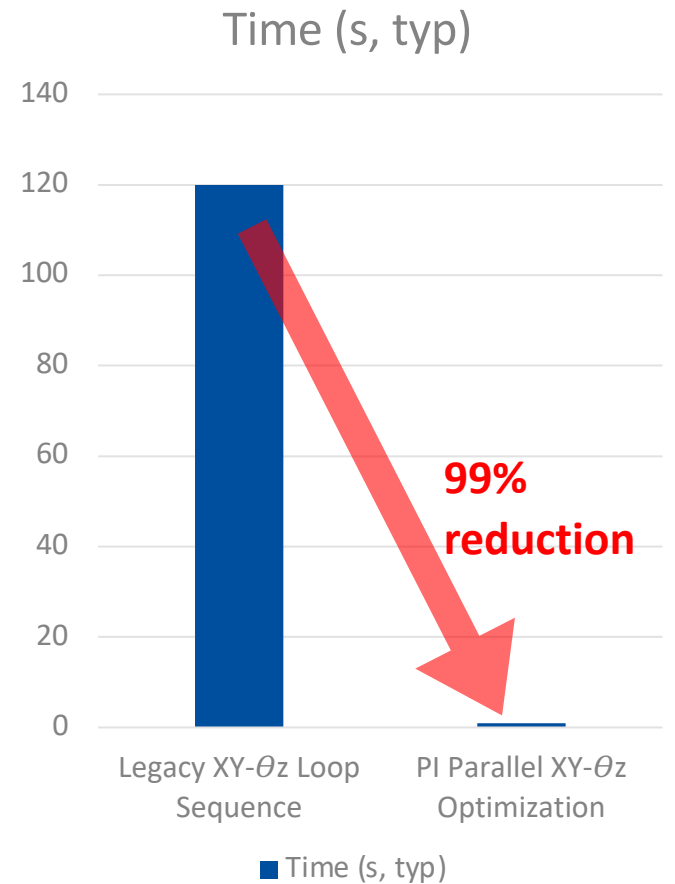
Unique: High-Speed Air Bearing stacks for Alignment

- Unlimited lifetime
- No lubricants
- Clean
- Up to 6DOF





PI's Novel Parallel Multi-DOF Optimization



New: Air Bearing Fast Alignment Engines

Super cleanliness

Zero maintenance, Zero wear

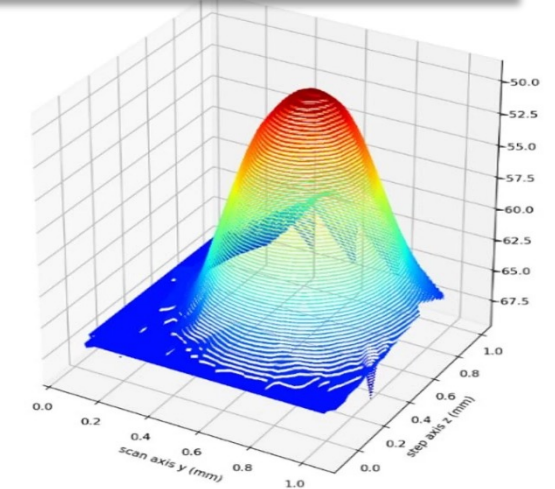
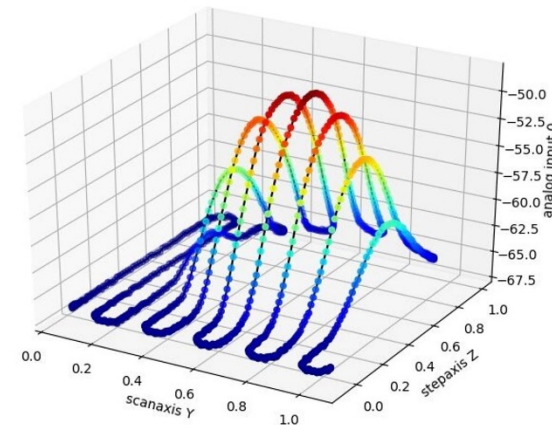
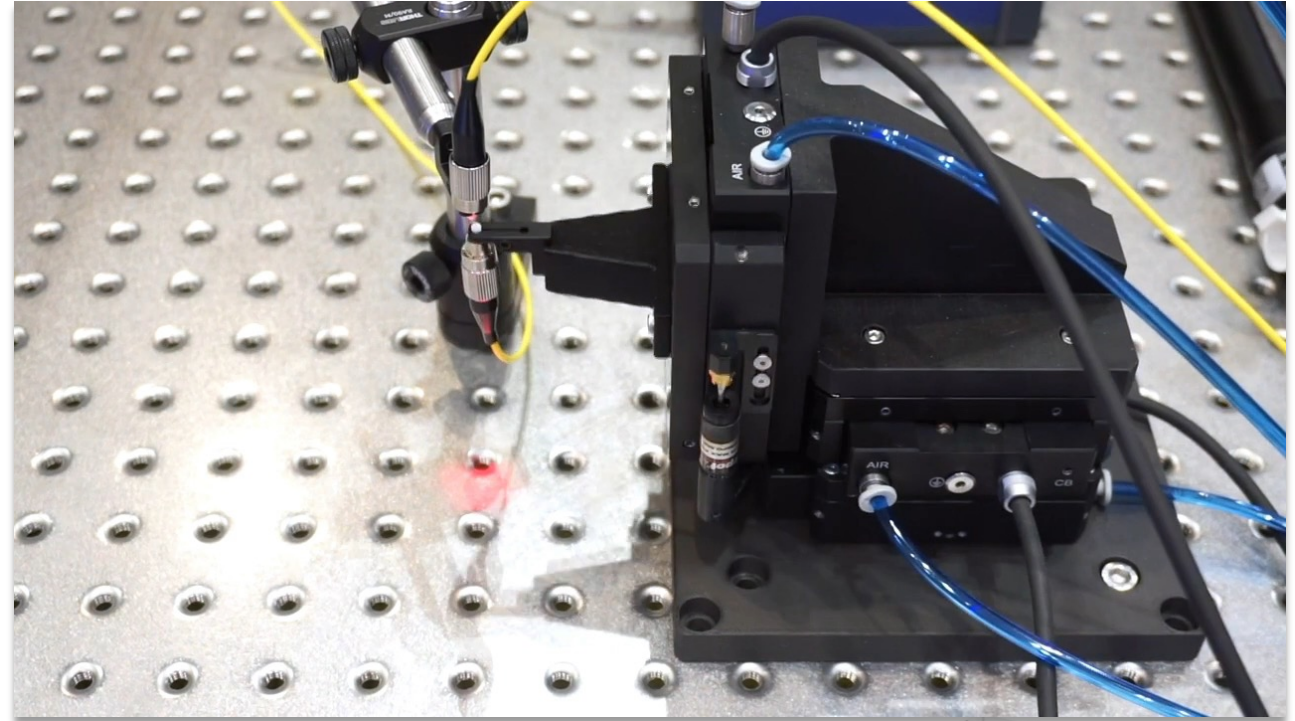
Highest MTBF

Fast Area Scan

- First light acquisition
- Profiling & characterization

Parallel Gradient Search

- Fast Optimization
- Real-time tracking across multiple DOFs
- Drift compensation
- Lock-on

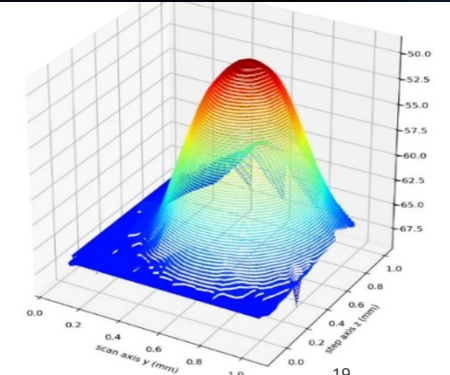
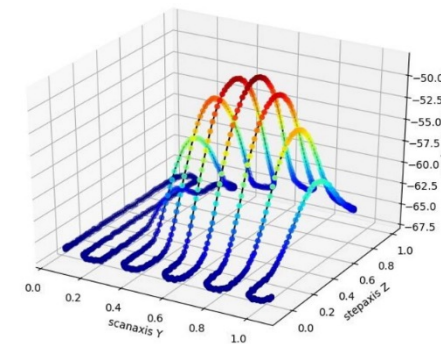


NEW: Revolutionary Fast First-Light Acquisition

PILightning: Solving the First-Light Problem

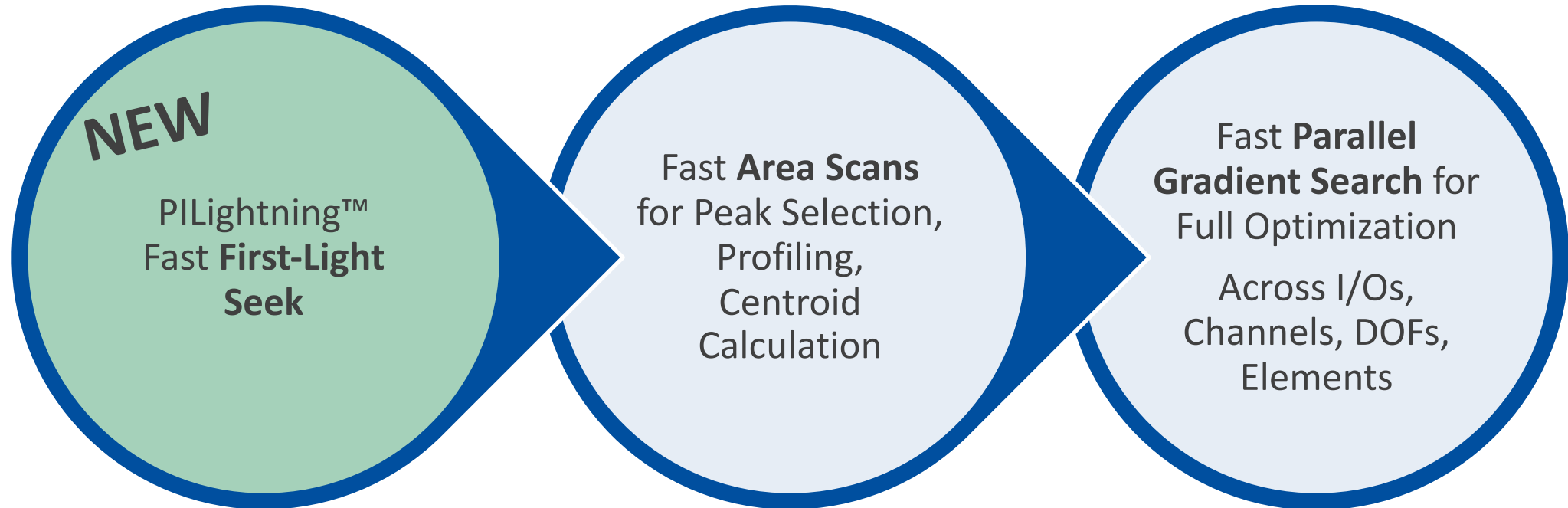
Now:

- *Typ. >10X faster first-light acquisition*
- *Even higher gains for double-sided first-light acquisition*
 - *Parallel first-light seek! Typ. <1sec*
- *Single command, fully autonomous, respects soft limits*
- *Integrated with full FMPA alignment suite*



NEW: Revolutionary Fast First-Light Acquisition

PILightning: Solving the First-Light Problem



The Ecosystem Emerges: Contract Manufacturing

The silent partner

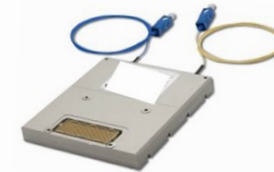
PI

- Photonic-competent players exist
 - Example: Fabrinet →
- Scalability
- Global presence
 - Geographically strategic

Optical Contract Manufacturing

fabrinet®

- Optical CM's, such as Fabrinet, have been around for 25 years
- Fabrinet is a trusted manufacturing partner of most of the industry OEM's
- Fabrinet can support from NPI to scaling for volume production
- They provide high quality, competitive costs, and global supply chain
- They are now supporting leading edge SiPh packaging



Fabrinet Confidential

Courtesy Fabrinet
Used with permission



The Ecosystem Emerges: Consortia and Foundries

The pathfinders

- Expertise from packaging concept to scaling

PI



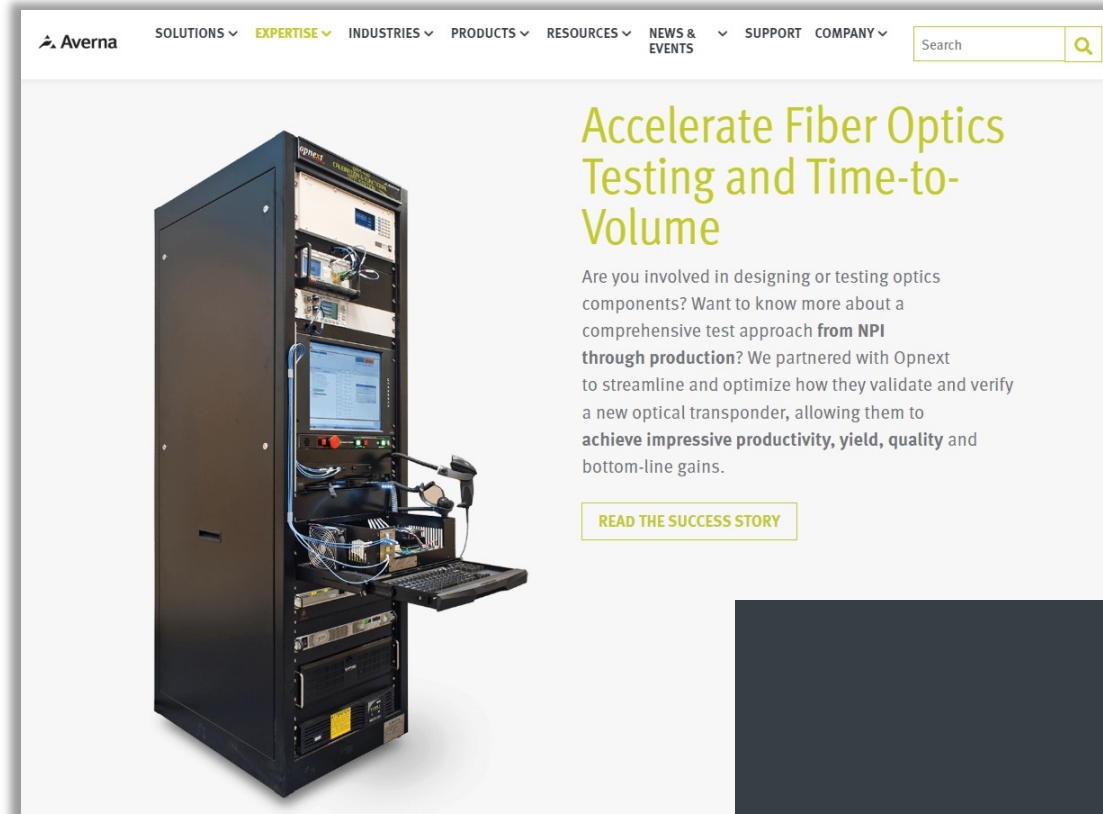
The screenshot shows the CITC website with a header featuring the CITC logo and navigation links. The main content area has a large image of a chip being mounted on a red substrate. Below the image is the text "Integration for Tomorrow" and a description of CITC as a non-profit joint innovation center specializing in heterogeneous integration and advanced chip packaging technology. A QR code is located in the bottom right corner of the screenshot.

The screenshot shows the phix website with a header featuring the phix logo and navigation links. The main content area has a large image of a photonic IC being mounted on a substrate. Below the image is the text "Packaging foundry for photonic ICs" and a button to watch a company video. The footer contains sections for "Our offering", "Fiber arrays", "About us", and "Lat", each with a brief description of the services provided. A QR code is located in the bottom right corner of the screenshot.

The Ecosystem Emerges: Systems Integrators

The builders

- Custom tools to accomplish mission-critical tasks
- From concept to scale
 - Example: Avera →



The Ecosystem Emerges: Toolmakers

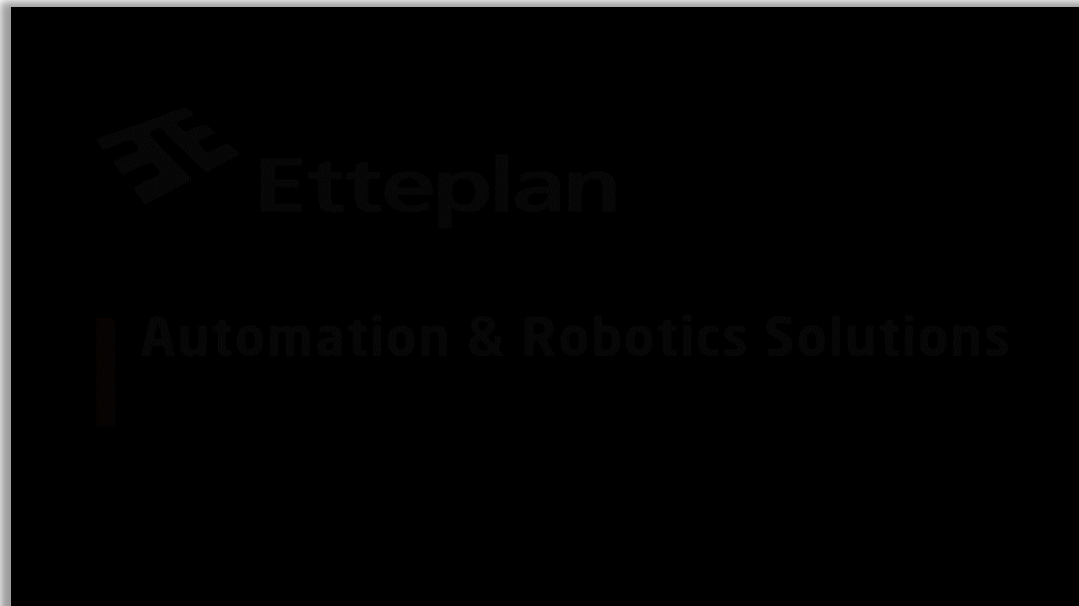
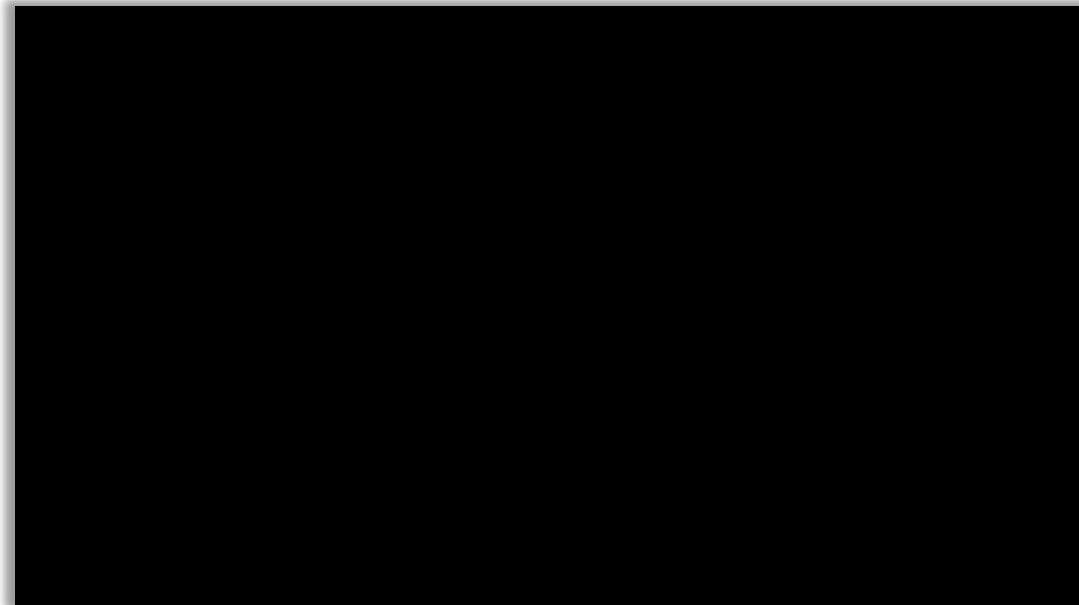
The avatars of market maturity

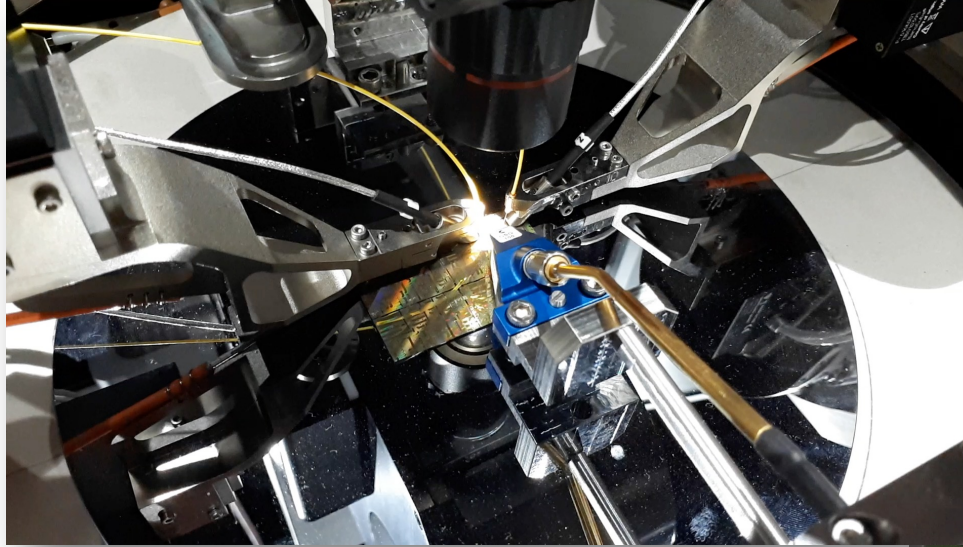
- Standard solutions for economic scaling

Examples:

FormFactor →
Wafer-test pioneer

Etteplan →
High-throughput assembly





Physik Instrumente

Keep in touch! ScottJ@pi-usa.us

PI USA HQ

16 Albert St
Auburn, MA, 01501

Email info@pi-usa.us

Visit us: www.pi-usa.us

PI Germany HQ

Auf der Roemerstrasse 1
76228 Karlsruhe, Germany

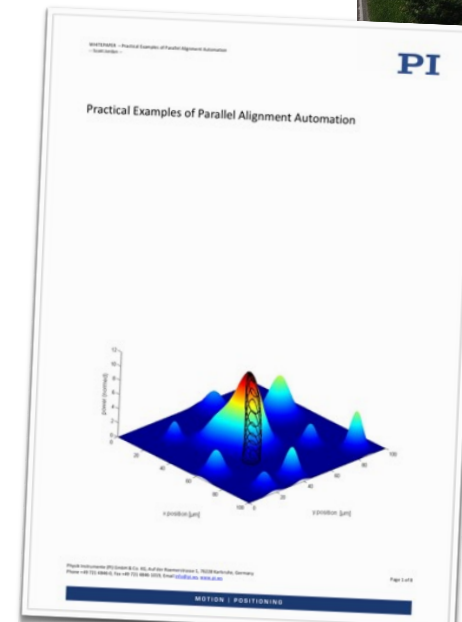
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Ask for a free Tech Note
on Parallelism in
Optimization

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